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Quarterly Reliability Monitoring Results

Quarters: Q1/2022 to Q4/2023

Based on structural similarity

Supplier		User Part Number						
Nexperia B.V. Name of Laboratory Assembly reliability labs Test		PMEG45A10EPD Part Description						
								Nexperia DHAM
		SMD package						
		Test Conditions Duration # Lots # Quantity # Reje						
			TEST					
	Pre- and Post-Stress							
# 1	Electrical Test	Tamb = 25 °C	N/A	see below	all parts	see below		
		JESD22-A113						
		Bake Tamb = 125 °C	24 hours					
	PC	Soak Tamb = 85 °C, RH = 85%	168 hours					
# 2	Preconditioning	Reflow soldering	3 cycles	1514	64430	0		
		MIL-STD-750-1						
	HTRB	M1038 Method A Tj = Tjmax, Vr = 100% of max. datasheet						
<i>#</i> F	Bias	reverse voltage ^[1]	1000 have	200	0220	0		
# 5	Bids	Teverse voltage	1000 hours	206	9320	0		
	тс	JESD22-A104						
# 7	Temperature Cycling	-65 °C to Tjmax, not to exceed 150°C	500 cycles	311	14080	0		
# /	· · · · · · · · · · · · · · · · · · ·		500 cycles	511	14000	0		
	UHAST	JESD22-A118						
# 8 or	Unbiased HAST	Tamb = 130 °C, RH = 85 %	— 96 hours	311	14080	0		
		JESD22-A102						
	AC	Tamb = 121 °C, RH = 100 %						
# 8a	Autoclave	Pressure = 205 kPa (29.7 psia)						
	H3TRB	JESD22-A101						
	High Humidity High	Tamb = 85 °C, RH = 85%, VR = 80 % of						
# 9	Temperature Reverse Bias	rated reverse voltage ^{[1], [2]}	1000 hours	311	14080	0		
		MIL-STD-750 Method 1037						
	IOL	ton = toff, devices powered to insure $\Delta T j$ =						
# 10	Intermittent Operating Life	100 °C	333 hours	312	14120	0		
" 20	RSH Resistance to Solder Heat	JESD22-A111	10	262	0070	•		
# 20		200 - C = 3 - C	10 s	269	8070	0		
# 21	SD Solderability	J-STD-002		222	6660	0		
# 21	,	J-STD-002		222	6660	0		

[1] The physical limitations of Schottky diodes have to be considered (thermal runaway).

[2] The maximum applied voltage is limited by test chamber set up and does not exceed 115V.

Calculation of FIT and MTTF

Test considered for FIT calculation: High Temperature Reverse Bias (HTRB, Test # 5) Confidence level 60%, derated to 55 °C, activation energy 0.7 eV, test time 168 to 1000 hours

Wafer Fab 1	Technology	Quantity	Rejects	Failure Rate (FIT)	MTTF (hrs)
Nexperia					
DHAM S	Schottky	9320	0	0,46	2,19E+09

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